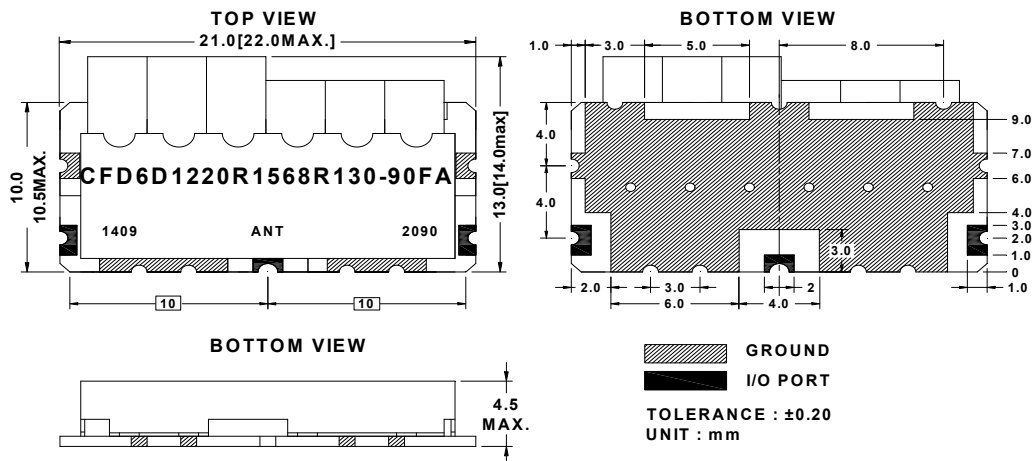


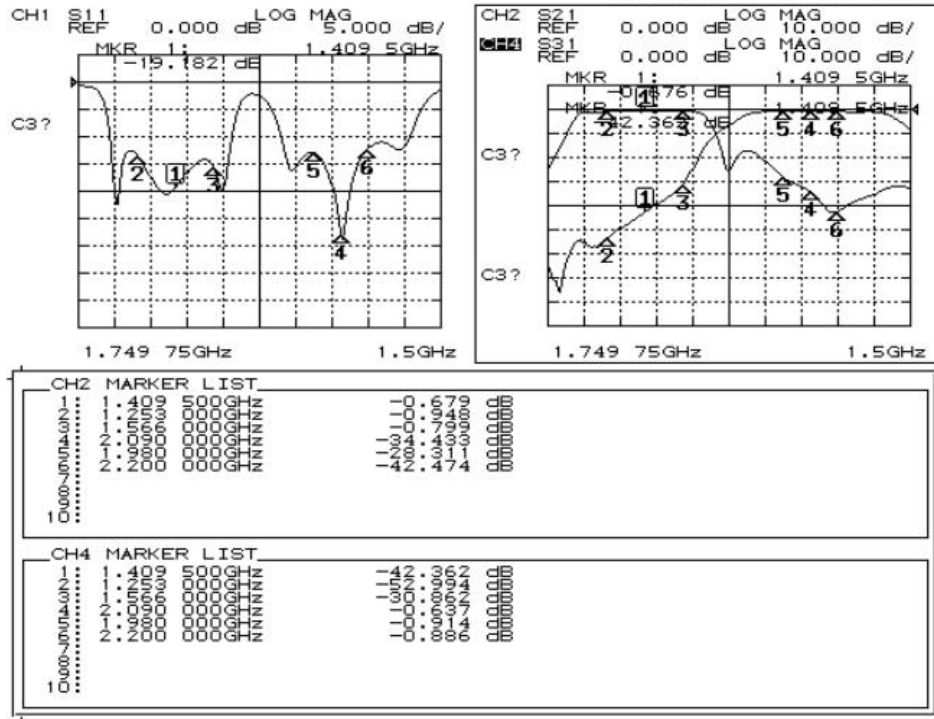
Electrical Specification

ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	1220	1586.5	MHz
Bandwidth [BW]	fo ±65 [1155.0~1285.0]	fo ±45.0 [1523.5~1613.5]	MHz
Insertion Loss in BW	1.5	2.0	dB max
Ripple in BW	0.5	0.5	dB max
Return Loss in BW	15.0	15.0	dB min
Attenuation <input checked="" type="checkbox"/> Absolute Value <input type="checkbox"/> Relative Value	40 dBmin.@[1523.5~1613.5]	40 dBmin.@[1155~1285]	MHz
	dBmin. @ [ ~ ]	dBmin. @ [ ~ ]	MHz
	Bmin. @ [ ~ ]	Bmin. @ [ ~ ]	MHz
	dBmin. @ [ ~ ]	dBmin. @ [ ~ ]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40°C to +85°C		

Mechanical Specification

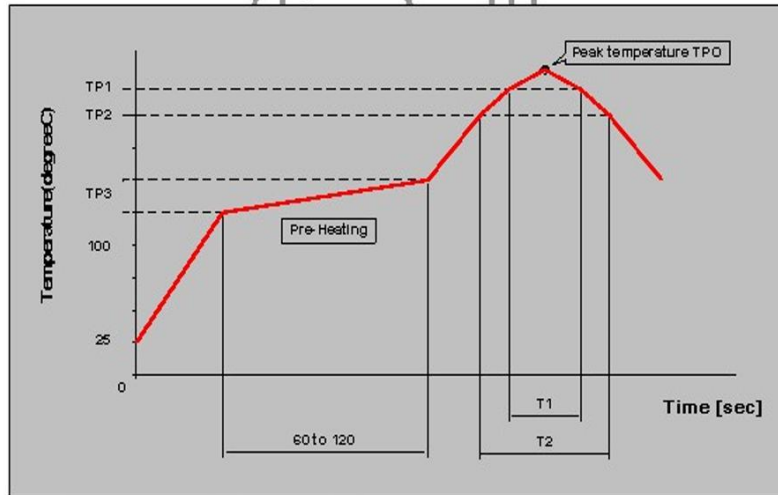


 Plot Data



 Recommended PC Board Pattern

 Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TP0 (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245±/5	220	30 to 60	—	—	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180